

MECHANICAL CASE OUTLINE

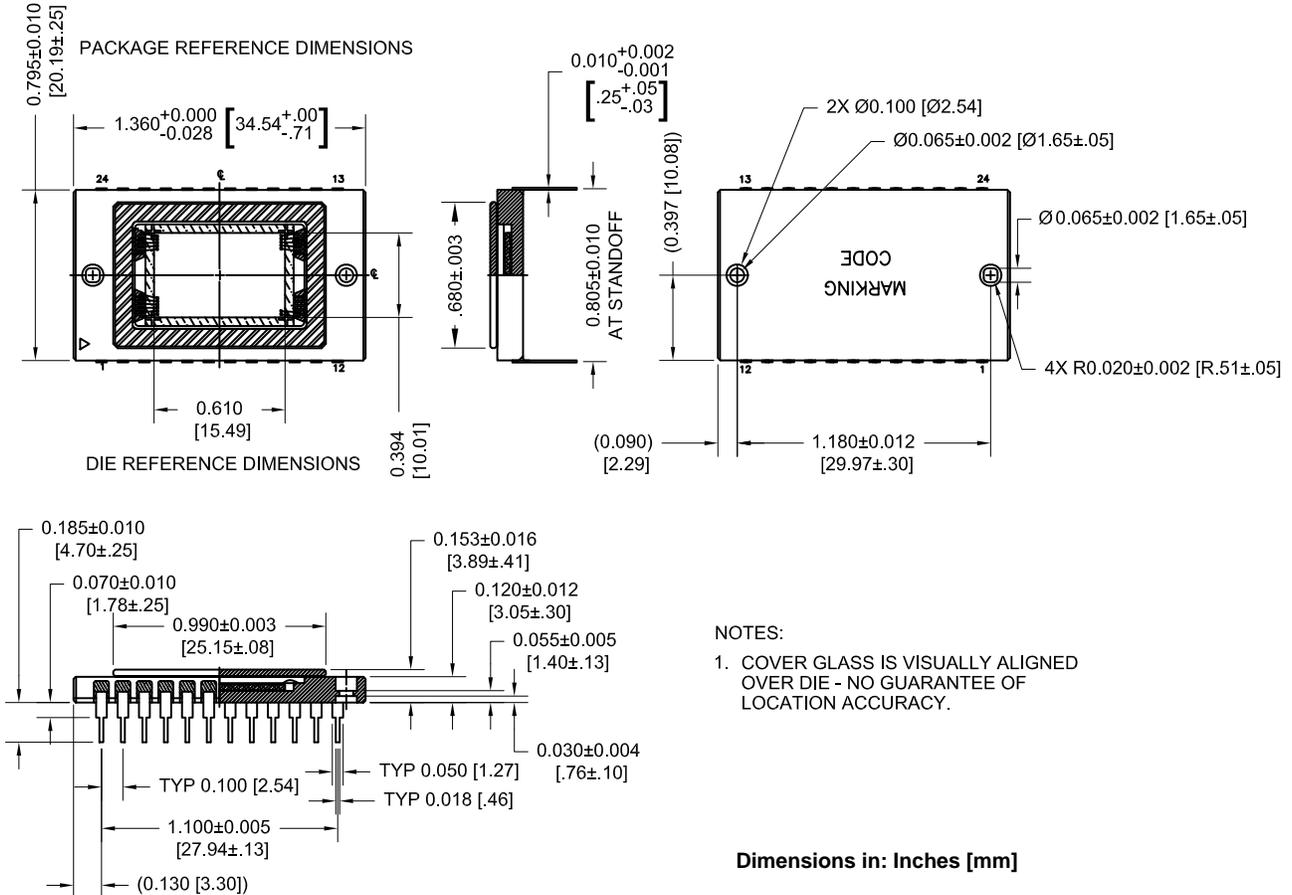
PACKAGE DIMENSIONS

ON Semiconductor®



CERAMIC DIP 24 CASE 125AU ISSUE O

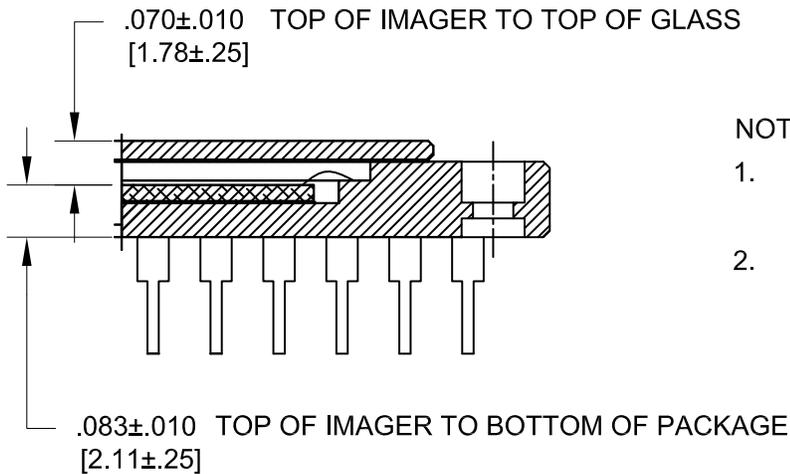
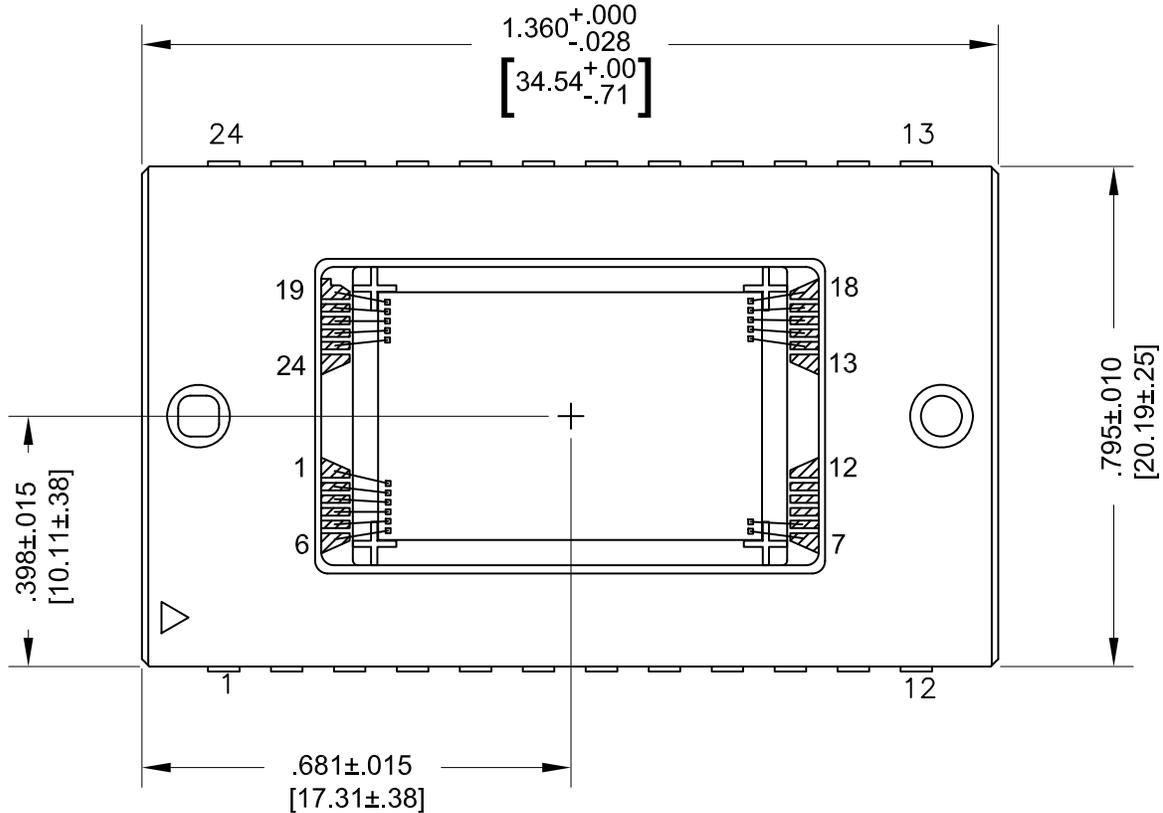
DATE 30 JUN 2014



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NOTES:

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.04,0.00)mm NOMINAL.
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